

Bridging Technology
Sharing Innovation

Call for Paper

The 15th Electronic Circuits World Convention (ECWC15) is the most notable international PCB symposium held every three years in different cities around the world. In the last 40 years, members of the World Electronics Circuit Council (WECC) have taken turns to host this conference.

HKPCA is honored to host ECWC15 in 2020. The conference is scheduled to begin in Hong Kong on 30 November 2020 and conclude at the International Electronics Circuit Exhibition (Shenzhen) in South China on 2 December 2020. The ECWC teams hope to provide a valuable platform to encourage learnings amongst peers and provide the latest on global PCB demand, PCB manufacturing processes as well as technologies to enable them to better cope with the changing market dynamics for trends such as 5G, autonomous driving, smart world and much more. It also aims to promote the domestic PCB industry and economic activities in every country and every region.

We welcome local and international papers and invite you to participate in this international event that occurs only every 3 years...network and share experiences with peers in the PCB and electronics manufacturing industry. For the submission of an abstract for ECWC15, please use our submission form as the attached.



30/11–1/12/2020 @Hong Kong
2/12/2020 @Shenzhen

Paper Scope

Technology

- T1 Design and Development Tools
- T2 Materials, Components and Traceability
- T3 Manufacturing
 - T3.1 Equipment
 - T3.2 Technology
 - T3.3 Process Development
 - T3.4 Automation
- T4 Quality, Test and Life Cycle Management
- T5 PCB Processes
 - T5.1 Chemical Technology
 - T5.2 Mechanical Technology
 - T5.3 Optical Technology
- T6 Surface Mounting, Assembly and Interconnection

Management

- M1 Global Market Trends and Outlook
- M2 Supply Chain Management
- M3 Environment, Health and Safety
- M4 Business Models and Strategy
- M5 Certification and Qualifications
- M6 Total Cost of Ownership and Overall Equipment Efficiency (OEE)
- M7 Industry 4.0/Smart manufacturing
- M8 Traceability/Blockchain

- T7 Packaging Technology
 - T7.1 System in Package
 - T7.2 Wafer-Level Packaging
 - T7.3 Panel-Level Packaging
- T8 Energy Harvesting/Green Energy
- T9 Application Specific Areas
 - T9.1 Automotive Electronics and Electromobility
 - T9.2 Industrial and Power Electronics
 - T9.3 Aerospace and Defence
 - T9.4 Medical Electronics
 - T9.5 Consumer Electronics
- T10. Advanced and Emerging Technologies
- T11. 5G Requirements on PCBs
- T12. Smart Living Applications
- T13. E-Textiles/Smart Textiles
- T14. Printed Electronics/Printed Hybrid



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Presentation formats

There are two opportunities for presenting your expertise:

✧ Oral presentation

These will be held within conference sessions addressing key elements of the same topic. Each presentation should last 20 minutes. An extra 5 minutes will be permitted for discussions and questions from the audience.

✧ Poster presentation

Authors will have the chance to present their posters during a special poster session.

Submission Deadline

Abstract submission.....	1 December 2019 - 29 February 2020
Abstract acceptance notification.....	30 April 2020
Full Paper submission.....	30 June 2020
Final acceptance notification.....	31 August 2020
Oral presentation (PPT) / Poster presentation material submission.....	31 October 2020

Abstract Submission

The synopsis/abstract should be submitted to

ecwc15@hkpca.org as pdf-file and should comprise of 500-800 words.

(Online submission information to be available later)

Selection Process

All submitted abstracts will be presented to the committee for selection. The acceptance of your abstract depends on the following criteria: the content, the preparation, the substance and the relevance of the conference themes. Punctuality and completeness are also criteria. The committee reserves the right to allocate abstracts to a different topic when suitable

Best Paper Award

The ECWC15 Program Committee will nominate the best abstracts out of all submissions. After the submission of the final papers the winners of the Best Paper Awards will be determined. The awards ceremony will take place on 2 December 2020.

Date / Place

- ✧ 30 November to 1 December 2020:
Hong Kong Science Park, Shatin
- ✧ 2 December 2020:
Shenzhen Convention & Exhibition Center, China
- ✧ 2-4 December 2020: in conjunction with “International Electronics Circuit Exhibition (Shenzhen)”

Organizer

Hong Kong Printed Circuit Association (HKPCA)

Co- Organizer

WECC members:

- China Printed Circuit Association (CPCA)
- European Institute of Printed Circuits (EIPC)
- Electronic Industries Association of India(ELCINA)
- Association Connecting Electronics Industries (IPC)
- Indian Printed Circuit Association (IPCA)
- Korea Printed Circuit Association (KPCA)
- Japan Electronics Packaging and Circuits Association (JPCA)
- Taiwan Printed Circuit Association (TPCA)
- Thailand Electronic Packaging and Circuits Association (THPCA)

Implementation Organization

Hong Kong Productivity Council

Funded by

ITC, GSP from Hong Kong SAR



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Enquiry

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Paper Submission Application Form

(Please send this filled form to ecwc15@hkpca.org)

Abstract submission: 1 December 2019 - 29 February 2020



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Author (Speaker) Information

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Given Name		Family Name	
Company		Postal address (full postal address including street, zip code and city)	
Position		Country	
Email		Join Paper Award	<input type="checkbox"/> Yes <input type="checkbox"/> No
Phone	() Ext	Mobile	
Wechat ID (if any) or other internet communication apps ID (please specify the application's name)			

Paper Information

Paper Title		Preferred Presentation Type	<input type="checkbox"/> Poster <input type="checkbox"/> Oral
		Association member	<input type="checkbox"/> HKPCA <input type="checkbox"/> CPCA <input type="checkbox"/> EIPC <input type="checkbox"/> ELCINA <input type="checkbox"/> IPC <input type="checkbox"/> IPCA <input type="checkbox"/> KPCA <input type="checkbox"/> JPCA <input type="checkbox"/> THPCA <input type="checkbox"/> TPCA
Additional Author(s)		Code of Paper Scope (e.g: T1, M1)	
Abstract (Within 500-800 words)			